

AN: PAT 2002-564031

TI: Ball grid array package

PN: KR2002016126-A

PD: 04.03.2002

AB: NOVELTY - A ball grid array package is provided to effectively reduce mechanical stress and to improve the capacity of the package, by improving the structure of a moisture relief of the package so that moisture in the package is smoothly emitted through a vent hole of a slot type. DETAILED DESCRIPTION - A plurality of solder pads have the first and second surfaces. A chip settle region is formed on the first surface. A solder ball(6) is attached to the second surface. The vent hole(100) of a slot type has a length from the center portion of the chip settle region to its outer direction, formed on the chip settle region and penetrating the first and second surfaces. A circuit board(1) includes the solder pads and the vent hole. Adhesive(2) is applied on the chip settle region of the circuit board. A semiconductor chip(3) is attached to the circuit board by using the adhesive, positioned on the chip settle region of the circuit board to cover the vent hole. At least one conductive connection member(4) electrically connects the semiconductor chip with the circuit board. Encapsulation resin(5) encapsulates the semiconductor chip, the conductive connection member and a predetermined portion of the first surface.;

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FA: KR2002016126-A 04.03.2002;

CO: KR;

IC: H01L-023/28;

MC: U11-E02A1;

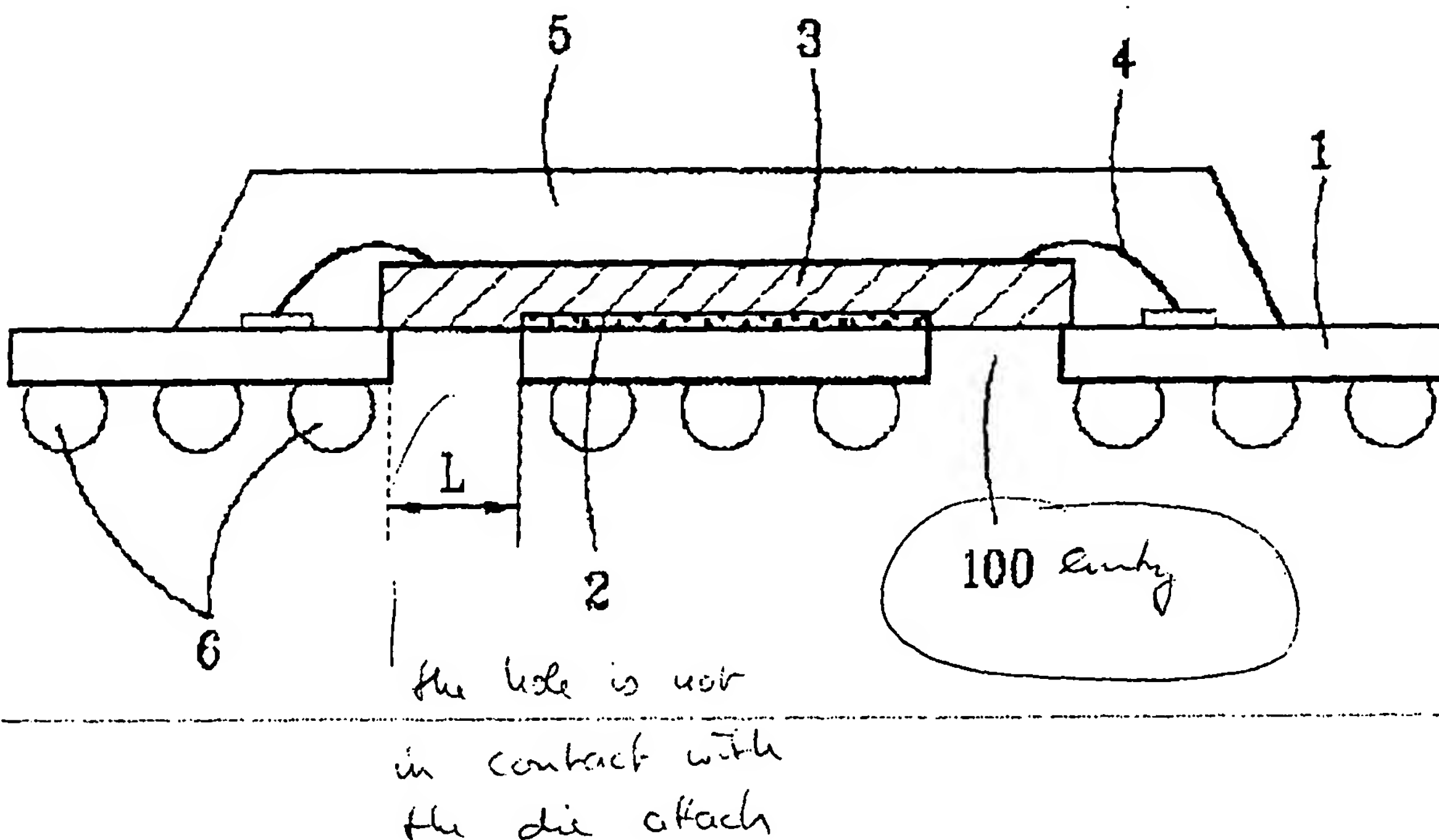
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